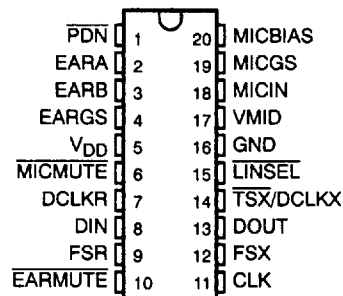


TCM320AC40, TCM320AC41 VOICE-BAND AUDIO PROCESSORS

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- **Single 5-V Operation**
- **Low Power Consumption:**
 - Operating Mode . . . 40 mW Typ
 - Standby Mode . . . 5 mW Typ
 - Power-Down Mode . . . 1.25 mW Typ
- **Combined ADC, DAC, and Filters**
- **Extended Variable-Frequency Operation**
 - Sample Rates up to 24 kHz
 - Pass-Band up to 10 kHz
- **Electret Microphone Bias Reference Voltage Available**
- **Directly Drives a Piezo Speaker**
- **Compatible With All DSPs**
- **Selectable Between 8-Bit Companded and 13-Bit (Dynamic Range) Linear Conversion:**
 - TCM320AC40 . . . μ -Law and Linear Modes
 - TCM320AC41 . . . A-Law and Linear Modes
- **Programmable Volume Control in Linear Mode**
- **Designed for Standard 1.152-MHz Master Clock for DEC and PCN Hand-Held Battery-Powered Telephones**

DW OR N PACKAGE
(TOP VIEW)



description

The voice-band audio processor circuits are designed to perform the transmit encoding (A/D conversion) and receive decoding (D/A conversion) together with transmit and receive filtering for voice-band communications systems. In particular, cellular telephone systems are targeted; however, this integrated circuit can function in several systems, including digital audio, telecommunications, and data acquisition.

The converted data is available in two formats. The formats are pin selectable between companded and linear. When the device is in the companded mode, data is transmitted and received in 8-bit words. When the linear mode is selected, 13 bits of data are sent and received, padded with zeros to provide a 16-bit word.

The transmit section is designed to directly interface with an electret microphone element. A reference voltage equal to $V_{DD}/2$, called VMID, is used to develop the mid-level virtual ground for all the amplifier circuits and the microphone bias circuit. A reference voltage called MICBIAS can be used to supply bias current for the microphone. The microphone input signal (MICIN) is buffered and amplified with provision for setting the amplifier gain to accommodate a range of signal input levels. The amplified signal is passed through antialiasing and band-pass filters. The filtered signal is then input to a compressing analog-to-digital converter (COADC), if companded mode is selected. Otherwise, the analog-to-digital converter performs a linear conversion.



Caution. These devices have limited built-in protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

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VOICE-BAND AUDIO PROCESSORS

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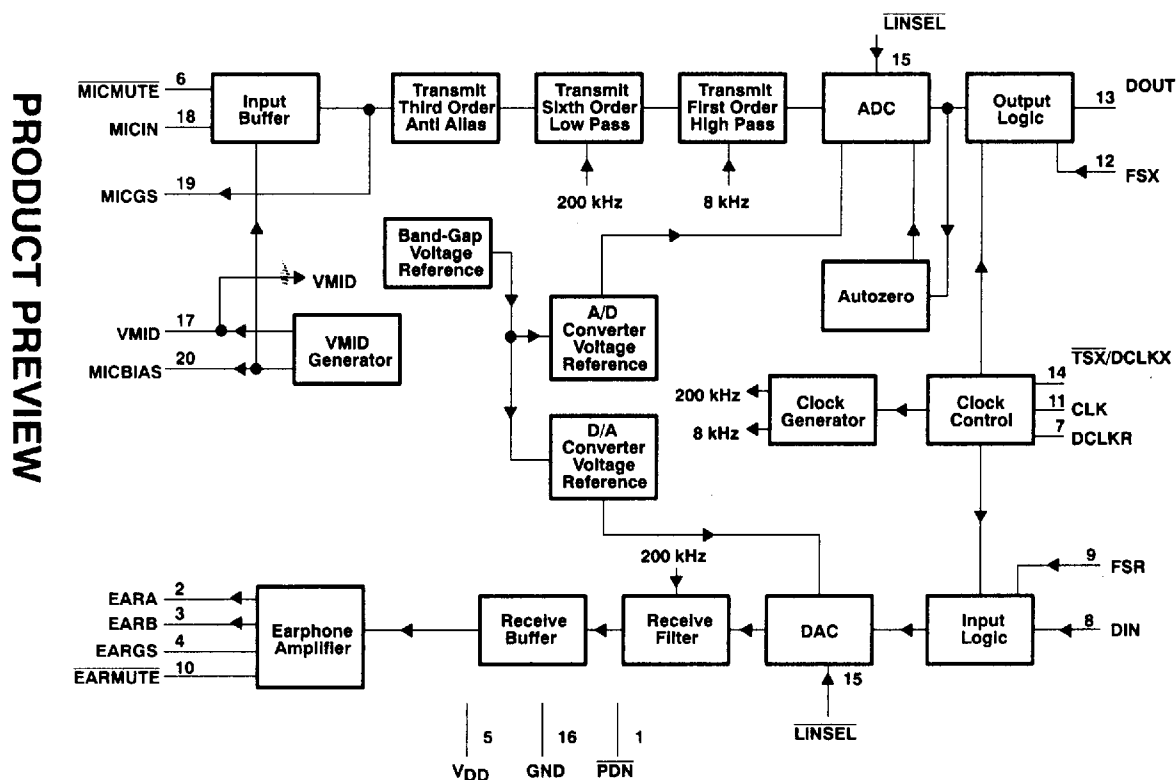
description (continued)

The receive section takes a frame of serial data on DIN and converts it to analog through an expanding digital-to-analog converter (EXDAC) if the companded mode is selected; otherwise, a linear conversion is performed. The analog signal then passes through switched capacitor filters, which provide out-of-band rejection, $(\sin x)/x$ correction functions, and smoothing. The filtered signal is sent to the earphone amplifier. The earphone amplifier has a differential output with adjustable gain that is designed to minimize static power dissipation.

A single on-chip, high-precision band-gap circuit generates all voltage references, eliminating the need for external reference voltages.

The TCM320AC4_C devices are characterized for operation from 0°C to 70°C. The TCM320AC4_I devices are characterized from -40°C to 85°C.

functional block diagram



TCM320AC40, TCM320AC41 VOICE-BAND AUDIO PROCESSORS

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Terminal Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
CLK	11	I	In the fixed-data-rate mode, this input is the master clock input as well as the transmit and receive data clock input. In the variable-data-rate mode, this input serves only as the master clock input.
DCLKR	7	I	Selects fixed- or variable-data-rate operation. When this input is connected to V _{DD} , the device operates in the fixed-data-rate mode. When DCLKR is not connected to V _{DD} , the device operates in the variable-data-rate mode and DCLKR becomes the receive data clock.
DIN	8	I	Receive data input. Input data is clocked in on consecutive negative transitions of the receive data clock, which is CLK in fixed-data-rate timing and DCLKR in variable-data-rate timing.
DOUT	13	O	Transmit data output. Transmit data is clocked out on consecutive positive transitions of the transmit data clock, which is CLK in fixed-data-rate timing and DCLKX in variable-data-rate timing.
EARA	2	O	Earphone output. This signal forms a differential drive when used with the EARB signal.
EARB	3	O	Earphone output. This signal forms a differential drive when used with the EARA signal.
EARGS	4	I	Earphone gain set input of feedback signal for the earphone output. The ratio of an external potential divider network connected across EARA and EARB adjusts the power amplifier gain. Maximum gain occurs when EARGS is connected to EARB and minimum gain occurs when EARGS is connected to EARA. Earphone frequency response correction can be performed using an RC approach.
EARMUTE	10	I	Earphone output mute control signal. When this input is low, the output amplifier is disabled and no audio is sent to the earphone.
FSR	9	I	Frame synchronization clock input for receive channel. In the variable-data-rate mode, this signal must remain high for the duration of the time slot. The receive channel enters the standby state when FSR is TTL low for five frames or longer. The device enters a production test-mode condition when either FSR or FSX are held high for five frames or longer.
FSX	12	I	Frame synchronization clock input for transmit channel. Operates independently of, but in an analogous manner to FSR. The transmit channel enters the standby state when FSX is low for five frames or longer. The device enters a production test-mode condition when either FSX or FSR are held high for five frames or longer.
GND	16		Ground return for all internal analog and digital circuits
LINSEL	15	I	Linear selection input. When low, selects linear coding/decoding. When high, selects companded coding/decoding.
MICBIAS	20	O	Bias voltage equal to VMID for the electret microphone
MICGS	19	O	Output of the internal microphone amplifier. This signal is used as the feedback to set the microphone amplifier gain. If sidetone is required, it may be accomplished by connecting a series network between MICGS and EARGS.
MICIN	18	I	Electret microphone input to the internal microphone amplifier
MICMUTE	6	I	Microphone input mute control signal. When this signal is active low, the input amplifier is disabled and the microphone current is switched off. Zero code is transmitted.
PDN	1	I	Power-down input. When low, the device powers down to reduce power consumption.
TSX/DCLKX	14	I/O	Transmit time slot strobe (low active output) or data clock (input) for the transmit channel. In the fixed-data-rate mode, this is an open-drain output that pulls to ground to be used as an enable signal for a 3-state buffer. In the variable-data-rate mode, DCLKX becomes the transmit data clock input.
V _{DD}	5		5-V supply voltage. Supply voltage for all internal analog and digital circuits.
VMID	17	O	V _{DD} /2 bias voltage reference. An external, low-leakage, high-frequency 1- μ F capacitor should be connected to this pin for filtering.

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**TCM320AC40, TCM320AC41
VOICE-BAND AUDIO PROCESSORS**

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general information**system reliability features**

The device should be powered up and initialized as follows:

1. GND is applied.
2. V_{DD} is applied.
3. All clocks are connected.
4. TTL high is applied to \overline{PDN} .
5. FSX and/or FSR synchronization pulses are applied.

Even though the VBAP is heavily protected against latch-up, it is still possible to cause it to latch-up under certain improper power conditions where excess current is forced into or out of one or more pins. To assure that latch-up will not occur, it is good design practice to put a reverse-biased Schottky diode between V_{DD} (power supply) and GND.

On the transmit channel, digital outputs DOUT and \overline{TSX} are held in the high-impedance state for approximately four frames (500 μ s) after power up or application of V_{DD} . After this delay, DOUT, \overline{TSX} , and signaling are functional and will occur in the proper time slot. The analog circuits on the transmit side require approximately 60 ms to reach their equilibrium value due to the autozero circuit settling time. To further enhance system integrity, DOUT and \overline{TSX} are placed in a high-impedance state after an interruption of CLK.

power-down and standby operations

To minimize power consumption, a power-down mode and three standby modes are provided.

For power down, an external low signal is applied to \overline{PDN} . In the absence of a signal, \overline{PDN} is internally pulled up to a high logic level, and the device remains active. In the power-down mode, the average power consumption is reduced to 1.25 mW.

The standby modes give the user the options of putting the entire device on standby, putting only the transmit channel on standby, or putting only the receive channel on standby. To place the entire device on standby, both FSX and FSR are held low. For transmit-only operation, FSX is pulsing and FSR is held low. For receive-only operation, FSR is pulsing and FSX is held low. In the standby mode with both transmit and receive in standby, power consumption is reduced to 5 mW.

See Table 1 for power-down and standby procedures.

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Table 1. Power-Down and Standby Procedures

DEVICE STATUS	PROCEDURE	TYPICAL POWER CONSUMPTION	DIGITAL OUTPUT STATUS
Power on	PDN = high, FSX = pulses, FSR = pulses	40 mW	Digital outputs active but not loaded
Power down	PDN = low, FSX/FSR = X/X	1.25 mW	$\overline{\text{TSX}}$ and DOUT in a high-impedance state
Entire device on standby	FSX = low, FSR = low, PDN = high	5 mW	$\overline{\text{TSX}}$ and DOUT in a high-impedance state
Only transmit on standby	FSX = low, FSR = pulses, PDN = high	20 mW	$\overline{\text{TSX}}$ and DOUT in a high-impedance state within 5 frames
Only receive on standby	FSR = low, FSX = pulses, PDN = high	20 mW	Digital outputs active but not loaded

fixed-data-rate timing

Fixed-data-rate timing is selected by connecting DCLKR to V_{DD} . It uses the master clock (CLK), frame synchronization clocks (FSX and FSR), and the $\overline{\text{TSX}}$ output. FSX and FSR are inputs that set the sampling frequency. Data is transmitted on the DOUT pin on the positive transitions of CLK following the rising edge of FSX. Data is received on the DIN pin on the falling edges of CLK following FSR. A D/A conversion is performed on the received digital word and the resulting analog sample is held on an internal sample-and-hold capacitor until transferred to the receive filter.

The data word is eight bits long in the companded mode and sixteen bits long in the linear mode.

variable-data-rate timing

Variable-data-rate timing is selected by connecting DCLKR to the receive data clock. In this mode, the master clock, CLK, controls the switched-capacitor filters, while data transfer into DIN and out of DOUT is controlled by DCLKR and DCLKX, respectively. This allows the data to be transferred into and out of the device at any rate up to the frequency of the master clock. DCLKR and DCLKX must be synchronous with CLK.

While the FSX input is high, DATA is transmitted from DOUT on consecutive positive transitions of DCLKX. Similarly, while the FSR input is high, the DATA word is received at DIN on consecutive negative transitions of DCLKR. The transmitted DATA word at DOUT is repeated in all remaining time slots in the frame as long as DCLKX is pulsed and FSX is held high. This feature, which allows the DATA word to be transmitted more than once per frame, is available only with variable-data-rate timing.

asynchronous operations

In order to avoid crosstalk problems associated with special interrupt circuits, the design includes separate converters, filters, and voltage references on the transmit and receive sides to allow completely independent operation of the two channels. In either timing mode, the master clock, data clock, and time slot strobe must be synchronized at the beginning of each frame.

precision voltage references

A precision band-gap reference voltage is generated internally and is used to supply all the references required for operation of both the transmit and receive channels. The gain in each channel is trimmed during the manufacturing process. This process ensures very accurate, stable gain performance over variations in supply voltage and device temperature.

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conversion laws

The TCM320AC40 provides μ -law companding operation as specified by CCITT G.711 recommendation.

The TCM320AC41 provides A-law companding operation as specified by CCITT G.711 recommendation.

The linear mode of operation is the same for both the TCM320AC40 and the TCM320AC41. The linear mode utilizes a 13-bit 2s complement format.

transmit operation

microphone input

The microphone input amplifier is specifically designed to interface to electret-type microphone elements as shown in Figure 1. The VMID buffer circuit provides a voltage (MICBIAS) equal to $1/2 V_{DD}$ as a reference for the microphone amp and a bias voltage to the electret microphone. The microphone amplifier output (MICGS) is used in conjunction with a feedback network to the amplifier inverting input (MICIN) to set the amplifier gain. VMID is brought out to provide a place to filter the VMID voltage.

microphone mute function

The MICMUTE input disables the microphone amplifier and attenuates the signal on the MICGS output to a level that is 80 dB or more down from the signal on the MICIN input. The MICMUTE also causes the digital circuitry to transmit all zero code of DOUT.

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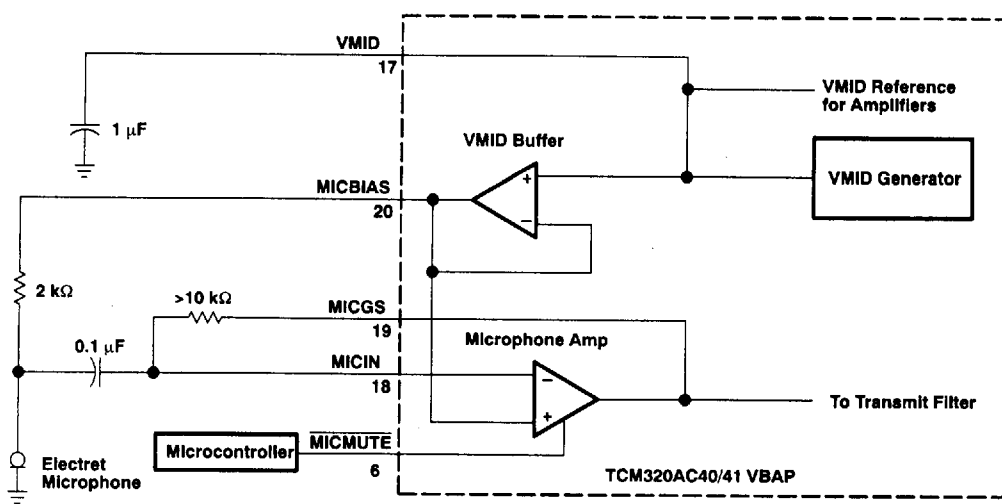


Figure 1. Typical Microphone Interface

transmit filter

A low-pass antialiasing section is included on the device. This section provides 35-dB attenuation at the sampling frequency. No external components are required to provide the necessary antialiasing function for the switched-capacitor section of the transmit filter.

encoding

The encoder internally samples the output of the transmit filter and holds each sample on an internal sample-and-hold capacitor. The encoder performs an analog-to-digital conversion on a switched-capacitor array. Digital data representing the sample is transmitted on the first 8 or 16 data clock cycles of the next frame.

The autozero circuit corrects for dc offset on the input signal to the encoder using the sign-bit averaging technique. The sign bit from the encoder output is long-term averaged and subtracted from the input to the encoder.

data word structure

The data word is 8 bits long in the companded mode. All 8 bits represent one audio data sample. The sign bit is the first bit transmitted.

The data word is 16 bits long in the linear mode. The first 13 bits comprise the audio data sample and the last three bits are volume control in the receive direction (DIN) and zeros in the transmit direction (DOUT). The sign bit is transmitted first.

receive operation**decoding**

The serial DATA word is received at DIN on the first 8 clock cycles in fixed-data-rate and the last 8 clock cycles in variable-data-rate in the companded mode and the first 13 clock cycles in the linear mode. Digital-to-analog conversion is performed, and the corresponding analog sample is held on an internal sample-and-hold capacitor. This sample is transferred to the receive filter.

receive filter

The receive section of the filter provides pass-band flatness and stop-band rejection that fulfills both the AT&T D3/D4 specification and CCITT recommendation G.712. The filter contains the required compensation for the $(\sin x)/x$ response of such decoders.

receive buffer

The receive buffer contains the volume control.

earphone amplifier

The earphone amplifier has a balanced output to allow maximum flexibility in output configuration. The output amplifier is designed to directly drive a piezo earphone in the differential configuration without any additional external components. The output can also be used to drive a single-ended load with the output signal voltage centered around $V_{DD}/2$.

The receive channel output level can be adjusted between specified limits by connecting an external resistor network to EARGS.

receive data format

Eight bits of data are received in the companded mode. All 8 bits are valid. The sign bit is the first bit received.

Sixteen bits of data are received in the linear mode. The first 13 bits are the D/A code, and the remaining three bits form the volume control word. The volume control function is actually an attenuation control where the first bit received is the most significant. The maximum volume occurs when all three volume control bits are zero and eight levels of attenuation are selectable in 3-dB steps giving a maximum attenuation of 21 dB when all bits are 1s.

The volume control bits are not latched into the VBAP and must be present in each received data word.

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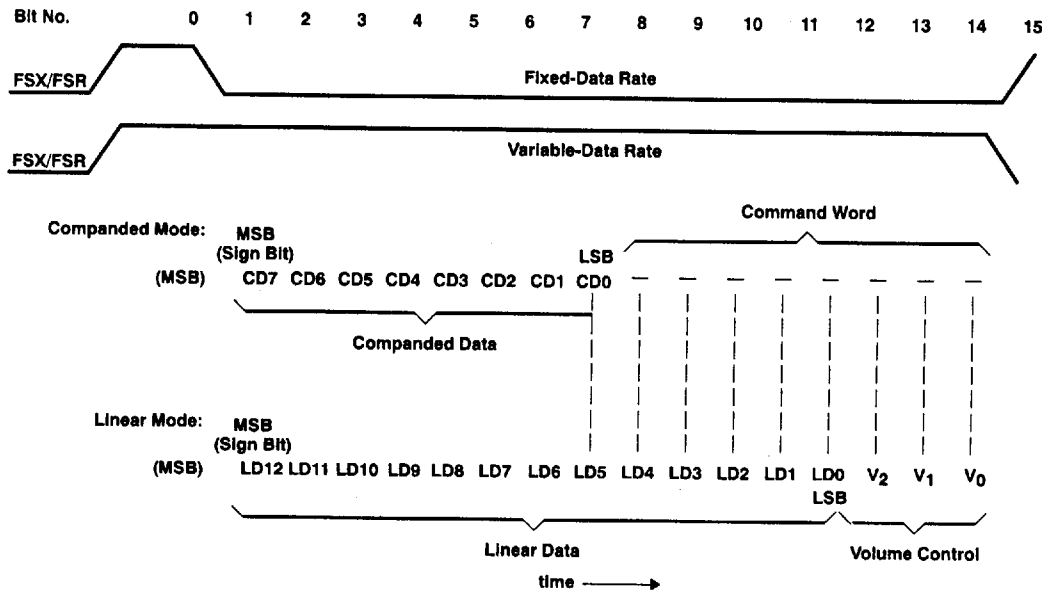
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Table 2. Receive Data Bit Definitions

BIT NO.	COMPANDED MODE	LINEAR MODE
0	CD7	LD12
1	CD6	LD11
2	CD5	LD10
3	CD4	LD9
4	CD3	LD8
5	CD2	LD7
6	CD1	LD6
7	CD0	LD5
8	-	LD4
9	-	LD3
A	-	LD2
B	-	LD1
C	-	LD0
D	-	V2
E	-	V1
F	-	V0

relationship between data word and frame sync

Volume control and other control bits always follow the PCM data in time:



where:

CD8-CD0 = Data word when in companded mode

— = Unused bits in companded mode

V2, V1, V0 = Volume (attenuation control) 000 = maximum volume, 3 dBm0

111 = minimum volume, -18 dBm0

LD12-LD0 = Data word when in linear mode

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{DD} (see Note 1)	-0.3 V to 7 V
Output voltage range, V_O , DOUT	-0.3 V to 7 V
Input voltage range, V_I , DIN	-0.3 V to 7 V
Ground voltage range, GND	-0.3 V to 7 V
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range: C-suffix	0°C to 70°C
I-suffix	-40°C to 85°C
Storage temperature range	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: Voltage value is with respect to GND terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING
DW	1025 mW	8.2 mW/°C	656 mW	533 mW
N	1150 mW	9.2 mW/°C	736 mW	598 mW

recommended operating conditions (see Note 2)

	MIN	MAX	UNIT
V_{DD} Supply voltage (see Note 3)	4.5	5.5	V
V_{IH} High-level input voltage	2.2		V
V_{IL} Low-level input voltage		0.8	V
R_L Load resistance between EARA and EARB (see Note 4)	600		Ω
C_L Load capacitance between EARA and EARB (see Note 4)		113	nF
T_A Operating free-air temperature	TCM320AC40C, TCM320AC41C		°C
		0	
	TCM320AC40I, TCM320AC41I		
	-40	85	

NOTES: 2. To avoid possible damage to these CMOS devices and resulting reliability problems, the following sequence should be followed when applying power:

1. Connect to GND
2. Connect V_{DD}
3. Connect the input signals

When removing power, follow the preceding steps in reverse order.

3. Voltages at analog inputs and outputs and V_{DD} are with respect to the GND terminal.
4. R_L and C_L should not be applied simultaneously.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**supply current, $f_{DCLK} = 1.152$ MHz, outputs not loaded**

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
I_{CC}	Supply current from V_{DD}	Operating	PDN = 1, CLK signal present		9.2	mA
		Power down	PDN = 0, after 500 μs		0.8	
		Standby - both	PDN = 1, FSX and FSR missing for 500 μs		1.8	
		Standby - one	PDN = 1, FSX or FSR missing for 500 μs		6	

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

digital interface

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH}	High-level output voltage	DOUT I _{OH} = -3.2 mA	2.4	4.6		V
V _{OL}	Low-level output voltage		I _{OL} = 3.2 mA	0.2	0.4	V
I _{IH}	High-level input current	Any digital input V _I = 2.2 V to V _{DD}			10	μA
I _{IL}	Low-level input current	Any digital input V _I = 0 to 0.8 V			10	μA
C _i	Input capacitance			5		pF
C _o	Output capacitance			5		pF

microphone interface‡

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IO}	Input offset voltage at MICIN	V _I = 2.5 V			±5	mV
I _{Ikg}	Input leakage current at MICIN				±200	nA
B ₁	Unity-gain bandwidth, open loop at MICIN			1		MHz
C _i	Input capacitance at MICIN				5	pF
A _v	Large-signal voltage amplification at MICGS				10000	V/V
	Output level at MICGS with MICMUTE active	V _I = 4 V			-80	dBm0
I _{O(max)}	Maximum output current	VMID		1		μA
		MICBIAS		1		mA

speaker interface‡

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
I _{IL}	Input leakage at EARGS	V _I = 0 to 5 V			±200	nA
V _{O(PP)}	AC output voltage peak-to-peak				3	V _{pp}
	Output offset voltage at EARA, EARB (single ended)	Relative to GND		80		mV
R _o	Output resistance at EARA, EARB			1		Ω
I _{O(max)}	Maximum output current	R ₁ = 60 Ω			±5	mA
A _v	Large-signal voltage amplification			4		V/V
	Gain change	EARMUTE low, max level when muted			-80	dB

transmit gain and dynamic range μ-law, A-law, or linear selected, V_{DD} = 5 V, T_A = 25°C (unless otherwise noted) (see Notes 5 and 6)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
Reference-signal level (0 dB)		μ-law		0.982	V _{rms}
		A-law		0.985	
		Linear		1.001	
Overload-signal level		μ-law		4	V _{pp}
		A-law		4	
		Linear		4	
Absolute gain error		0 dB input signal		±1	dB
Gain variation with input level relative to gain at -10 dB		3 dB to -40 dB		±0.5	dB
		-41 dB to -50 dB		±0.8	
		-51 dB to -55 dB		±1.5	
Gain variation		V _{DD} ± 10%, T _A = 0°C to 70°C		±0.5	dB

† All typical values are at V_{DD} = 5 V, T_A = 25°C.

‡ All parameters measured are between MICIN and GND (unless otherwise noted).

NOTES: 5. Unless otherwise noted, the analog input is 0 dB, 1020-Hz sine wave, where 0 dB is defined as the zero-reference point of the channel under test.

6. The input amplifier is set for inverting unity gain.

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transmit filter transfer, μ -law, A-law, or linear selected, over recommended ranges of supply voltage and free-air temperature, CLK = 1.152 MHz, FSX and FSR = 8 kHz (see Note 6)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT			
Gain relative to gain at 1.02 kHz	Input amplifier set for unity gain, noninverting maximum gain output signal at MICIN is 0 dB	50 Hz	-10	0	dB		
		200 Hz	-1.8	0			
		300 Hz to 3 kHz		± 0.15			
		3.3 kHz	-0.35	0.03			
		3.4 kHz	-1	-0.1			
		4 kHz		-14			
		4.6 kHz		-36			
				8 kHz		-46	

transmit idle channel noise and distortion

companded mode, μ -law or A-law selected over recommended ranges of supply voltage and operating free-air temperature (see Note 7)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Transmit noise, psophometrically weighted	MICIN connected to MICGS through a 10-k Ω resistor		-71	dB0p
Transmit noise, C-message weighted	MICIN connected to MICGS through a 10-k Ω resistor		10	dB0C
Transmit signal-to-distortion ratio with sine-wave input	0 to -30 dB		36	dB
	-31 dB to -40 dB		30	
	-41 dB to -45 dB		20	
Intermodulation distortion 2-tone CCITT method, composite power level -13 dBm0	R2		49	dB
	R3		51	

linear mode over recommended ranges of supply voltage and operating free-air temperature (see Notes 6 and 7)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Transmit noise	MICIN connected to MICGS through a 10-k Ω resistor	200		μ Vrms
Transmit signal-to-distortion ratio with sine-wave input	0 to -6 dB		54	dB
	-7 dB to -12 dB		48	
	-13 dB to -18 dB		42	
	-19 dB to -24 dB		35	
	-25 dB to -45 dB		23	

receive gain and dynamic range, $V_{DD} = 5$ V, $T_A = 15^\circ\text{C}$ (unless otherwise noted) (see Notes 8 and 9)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Reference-signal level (0 dB)	μ -law		0.736	Vrms
	A-law		0.739	
	Linear		0.751	
Overload-signal level	μ -law		3	Vpp
	A-law		3	
	Linear		3	
Absolute gain error	0-dB input signal		± 1	dB
Gain variation with output level relative to gain at -10 dBm0	3 to -40 dB		± 0.5	dB
	-41 dB to -50 dB		± 0.8	
	-51 dB to -55 dB		$\pm 0.1.2$	
Gain variation	$V_{DD} \pm 10\%$, $T_A = 0^\circ\text{C}$ to 70°C		± 0.5	dB

NOTES: 6. The input amplifier is set for inverting unity gain.

7. Transmit noise, linear mode: 200 μ Vrms is equivalent to -74 dB (referenced to device 0-dB level).

8. Receive output is measured differentially in the maximum gain configuration. To set the output amplifier for maximum gain, EARGS is connected to EARB, and the output is taken between EARA and EARB. All output levels are (sin x)/x corrected.

9. Unless otherwise noted, the digital input is a word stream generated by passing a 0-dB sine wave at 1020 Hz through an ideal encoder where 0 dB is defined as the zero reference.

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receive filter transfer over recommended ranges of supply voltage and operating free-air temperature (see Note 8)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT	
Gain relative to gain at 1.02 kHz	Input signal at DIN is 0 dBm0	< 200 Hz		0.15	dB
		200 Hz	-0.5	0.15	
		300 Hz to 3 kHz		±0.15	
		3.3 kHz	-0.35	0.03	
		3.4 kHz	-1	-0.18	
		4 kHz		-14	
		4.6 kHz		-38	
8 kHz		-50			

receive idle channel noise and distortion

companded mode, μ -law or A-law selected over recommended ranges of supply voltage and operating free-air temperature (see Note 8)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Receive noise, psophometrically weighted	DIN = 11010101 (A-law)		-75	dBm0p
Receive noise, C-message weighted	DIN = 11111111 (μ -law)		5	dBmrc0
Receive signal-to-distortion ratio with sine-wave input	0 to -30 dBm0, companded		36	dB
	-31 dBm0 to -40 dBm0, companded		30	
	-41 dBm0 to -45 dBm0, companded		25	

linear mode over recommended ranges of supply voltage and operating free-air temperature (see Notes 8 and 10)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Receive noise	DIN = 00000000 (linear)		200	μ V
Receive signal-to-distortion ratio with sine-wave input	0 to -6 dBm0, linear		52	dB
	-7 dBm0 to -12 dBm0, linear		48	
	-13 dBm0 to -18 dBm0, linear		42	
	-24 dBm0 to -45 dBm0, linear		20	
Intermodulation 2-tone CCITT distortion method, composite power level -13 dBm0	R2		50	dB
	R3		54	

power supply rejection and crosstalk attenuation over recommended ranges of supply voltage and operating free-air temperature

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Supply voltage rejection ratio, transmit channel	Idle channel, supply signal = 100 mV(RMS), f = 0 to 30 kHz (measured at DOUT)			-30	dB
Supply voltage rejection ratio, receive channel	Idle channel, supply signal = 100 mV(RMS), EARGS connected to EARB, f = 0 to 30 kHz (measured differentially between EARA and EARB)			-30	dB
Crosstalk attenuation, transmit-to-receive (differential)	MICIN = 0 dB, f = 1.02 kHz, unity transmit gain, EARGS connected to EARB, measured differentially between EARA and EARB		68		dB
Crosstalk attenuation, receive-to-transmit	DIN = 0 dBm0, f = 1.02 kHz, unity transmit gain, measured at DOUT		68		dB

† All typical values are at $V_{DD} = 5$ V, $T_A = 25^\circ$ C.

NOTES: 8. Receive output is measured differentially in the maximum gain configuration. To set the output amplifier for maximum gain, EARGS is connected to EARB, and the output is taken between EARA and EARB. All output levels are (sin x)/x corrected.

10. Receive noise, linear mode: 200 μ Vrms is equivalent to -71 dB (referenced to device 0-dB level).

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receive idle channel noise and distortion (continued)

clock timing requirements over recommended ranges of supply voltage and operating free-air temperature (see timing diagrams)

PARAMETER	MIN	TYP†	MAX	UNIT
t_t Transition time, CLK and DCLK			10	ns
Duty cycle, CLK	45%	50%	55%	
Duty cycle, DCLK	45%	50%	55%	

† All typical values are at $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

transmit timing requirement over recommended ranges of supply voltage and operating free-air temperature, fixed-data-rate mode (see timing diagrams)

PARAMETER	MIN	MAX	UNIT
$t_{su}(\text{FSX})$ Frame sync setup time	20	468	ns
$t_h(\text{FSX})$ Frame sync hold time	20	468	ns

propagation delay times over recommended ranges of operating conditions, fixed-data-rate mode (see timing diagrams)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
t_{pd1} From CLK bit 1 high to DOUT bit 1 valid	$C_L = 0$ to 10 pF		35	ns
t_{pd2} From CLK high to DOUT valid, bits 2 to n	$C_L = 0$ to 10 pF		35	ns
t_{pd3} From CLK bit n low to DOUT bit n Hi-Z	$C_L = 0$ to 10 pF	30		ns
t_{pd4} From CLK bit 1 high to TSX active (low)	$C_L = 0$ to 10 pF, $R_{pullup} = 1.24\text{ k}\Omega$		40	ns
t_{pd5} From CLK bit n low to FSX inactive (high)	$C_L = 0$ to 10 pF, $R_{pullup} = 1.24\text{ k}\Omega$	30		ns

receive timing requirement over recommended ranges of supply voltage and operating free-air temperature, fixed-data-rate mode (see timing diagrams)

PARAMETER	MIN	MAX	UNIT
$t_{su}(\text{FSR})$ Frame sync setup time	20	468	ns
$t_h(\text{FSR})$ Frame sync hold time	20	468	ns
$t_{su}(\text{DIN})$ Data in setup time	20		ns
$t_h(\text{DIN})$ Data in hold time	20		ns

transmit timing requirement over recommended ranges of supply voltage and operating free-air temperature, variable-data-rate mode (see timing diagrams)

PARAMETER	MIN	MAX	UNIT
$t_{su}(\text{FSX})$ Frame sync setup time	40	$t_c(\text{DCLKX}) - 40$	ns
$t_h(\text{FSX})$ Frame sync hold time	35	$t_c(\text{DCLKX}) - 35$	ns

propagation delay times over recommended ranges of operating conditions, variable-data-rate mode (see timing diagrams)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
t_{pd6} FSX high to DOUT bit 1 valid	$C_L = 0$ to 10 pF		30	ns
t_{pd7} DCLKX high to DOUT valid, bits 2 to n	$C_L = 0$ to 10 pF		40	ns
t_{pd8} FSX low to DOUT bit n Hi-Z		20		ns

receive timing requirements over recommended ranges of supply voltage and operating free-air temperature, variable-data-rate mode (see timing diagrams)

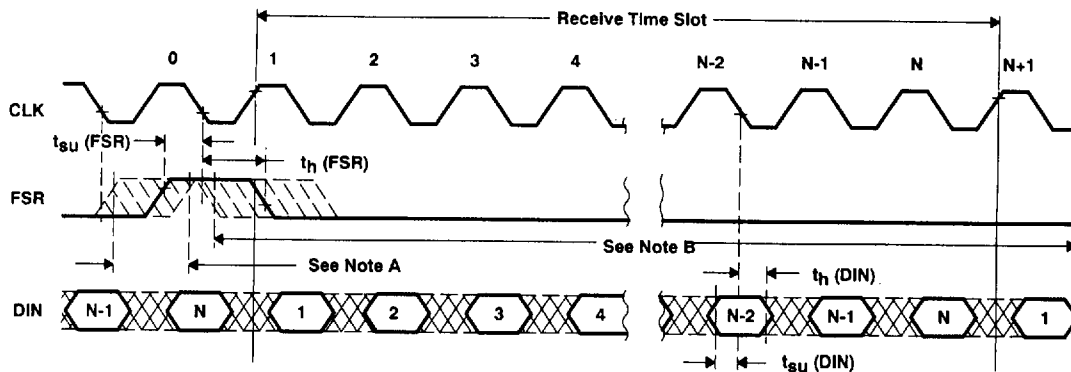
PARAMETER	MIN	MAX	UNIT
$t_{su}(\text{FSR})$ Frame sync setup time	40		ns
$t_h(\text{FSR})$ Frame sync hold time	35	$t_c(\text{DCLKR}) - 35$	ns
$t_{su}(\text{DIN})$ Data in setup time	30		ns
$t_h(\text{DIN})$ Data in hold time	30		ns

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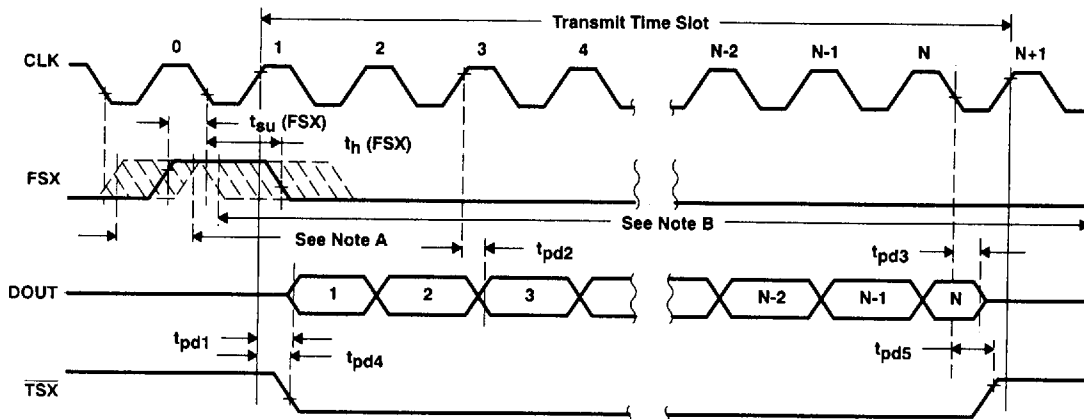
PARAMETER MEASUREMENT INFORMATION

All timing parameters are referenced to V_{IH} and V_{IL} . Bit 1 = MSB (most significant bit) and is clocked in first on DIN or clocked out first on DOUT. Bit n = LSB (least significant bit) and is clocked in last on DIN or is clocked out last on DOUT. N = 8 for the companded mode and N = 16 for the linear mode.



NOTES: A. This window is allowed for FSR high.
 B. This window is allowed for FSR low.

Figure 2. Fixed-Data-Rate, Receive Side Timing Diagram



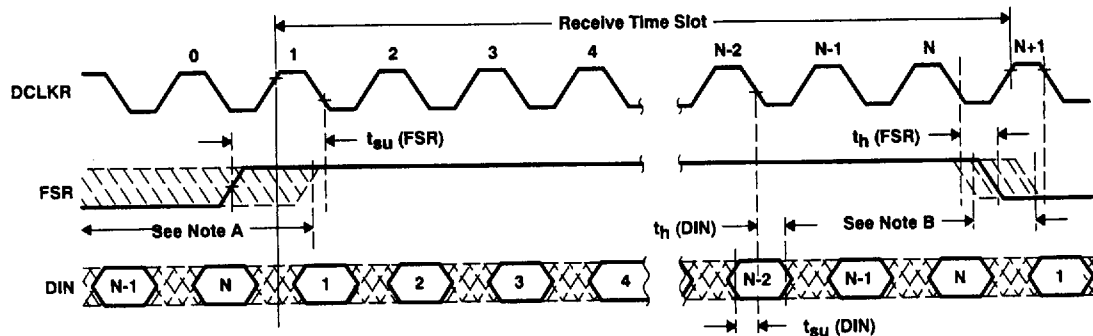
NOTES: A. This window is allowed for FSX high.
 B. This window is allowed for FSX low ($t_h(FSX)$ max determined by data collision considerations).

Figure 3. Fixed-Data-Rate, Transmit Side Timing Diagram

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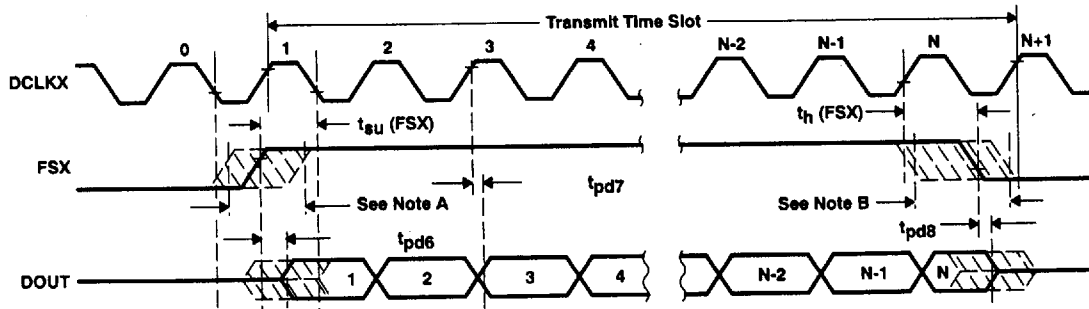
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PARAMETER MEASUREMENT INFORMATION



NOTES: A. This window is allowed for FSR high ($t_{su}(FSR)$ max determined by data collision considerations).
B. This window is allowed for FSR low.

Figure 4. Variable-Data-Rate, Receive Side Timing Diagram



NOTES: A. This window is allowed for FSX high.
B. This window is allowed for FSX low without data repetition..

Figure 5. Variable-Data-Rate, Transmit Side Timing Diagram

APPLICATION INFORMATION

output gain set design considerations (see Figure 6)

EARA and EARB are low-impedance complementary outputs. The voltages at the nodes are:

V_{O+} at EARA

V_{O-} at EARB

$V_{OD} = V_{O+} - V_{O-}$ (total differential response)

R1 and R2 are a gain-setting resistor network with the center tap connected to the EARGS input.

A value greater than 10 k Ω and less than 100 k Ω for R1 + R2 is recommended because of the following:

The parallel combination R1 + R2 and R_L sets the total loading. The total capacitance at the EARGS input and the parallel combination of R1 and R2 define a time constant that has to be minimized to avoid inaccuracies.

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APPLICATION INFORMATION

V_A represents the maximum available digital mW output response ($V_A = 1.06$ rms).

$$V_{OD} = A \times V_A$$

$$\text{where } A = \frac{1 + (R1/R2)}{4 + (R1/R2)}$$

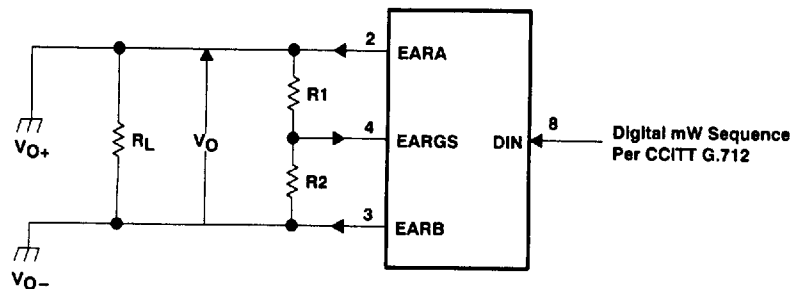


Figure 6. Gain-Setting Configuration

higher clock frequencies and sample rates

The VBAP is designed to work with sample rates up to 24 kHz where the frequency of the frame sync determines the sampling frequency. However, there is a fundamental requirement to maintain the ratio of master clock frequency, f_{CLK} , to frame sync frequency, f_{FSR}/f_{FSX} . This ratio for the VBAP is 1.152 MHz/8 kHz or 144 master clocks per frame sync.

For example, to operate the VBAP at a sampling rate of f_{FSR} and f_{FSX} equal to 16 kHz, f_{CLK} must be 144 times 16 kHz or 2.304 MHz.

If the VBAP is operated above an 8-kHz sample rate, however, it is expected that the performance will be somewhat degraded. Exact parametric specifications for rates up to 24-kHz sample rate are not specified at this time.

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